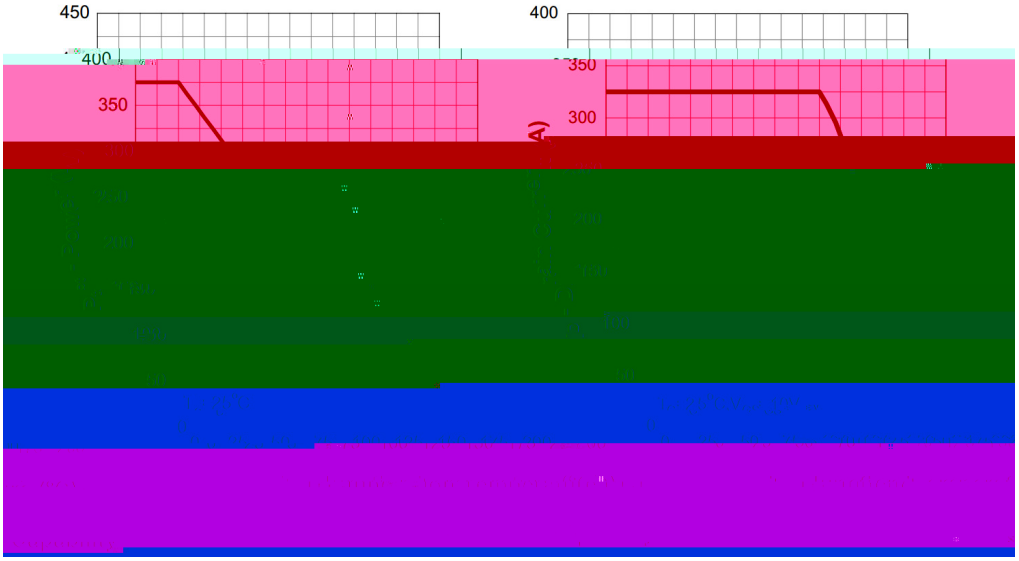
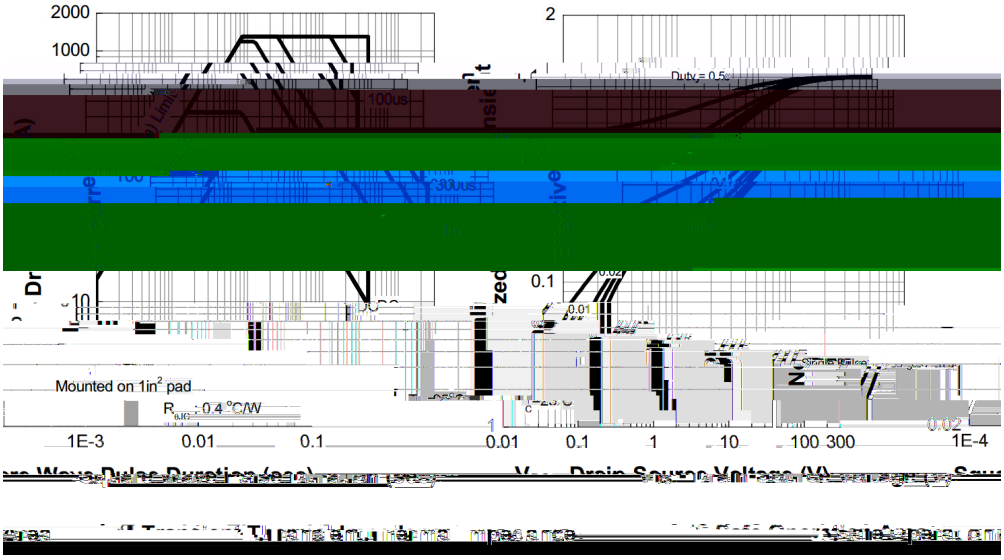
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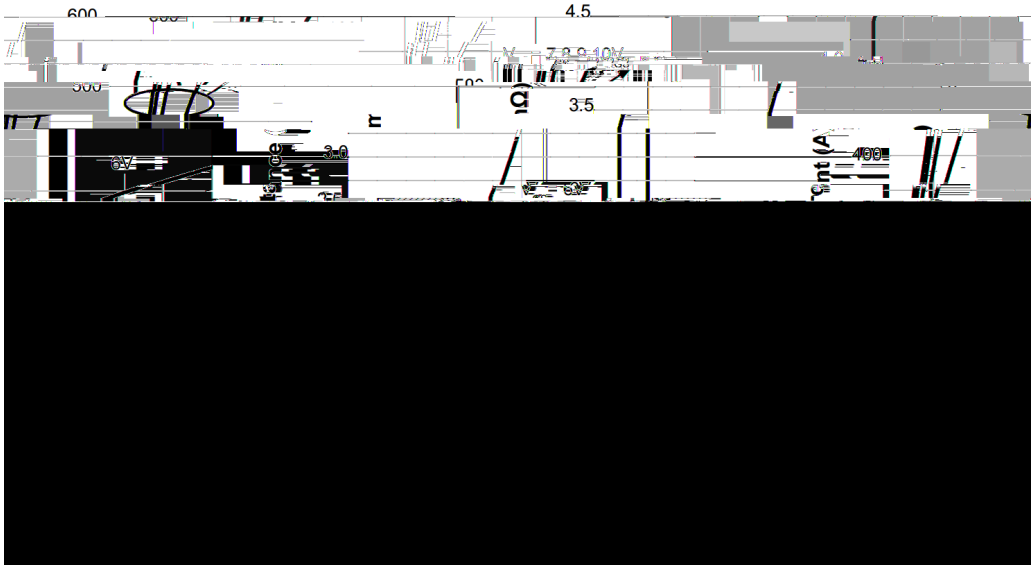
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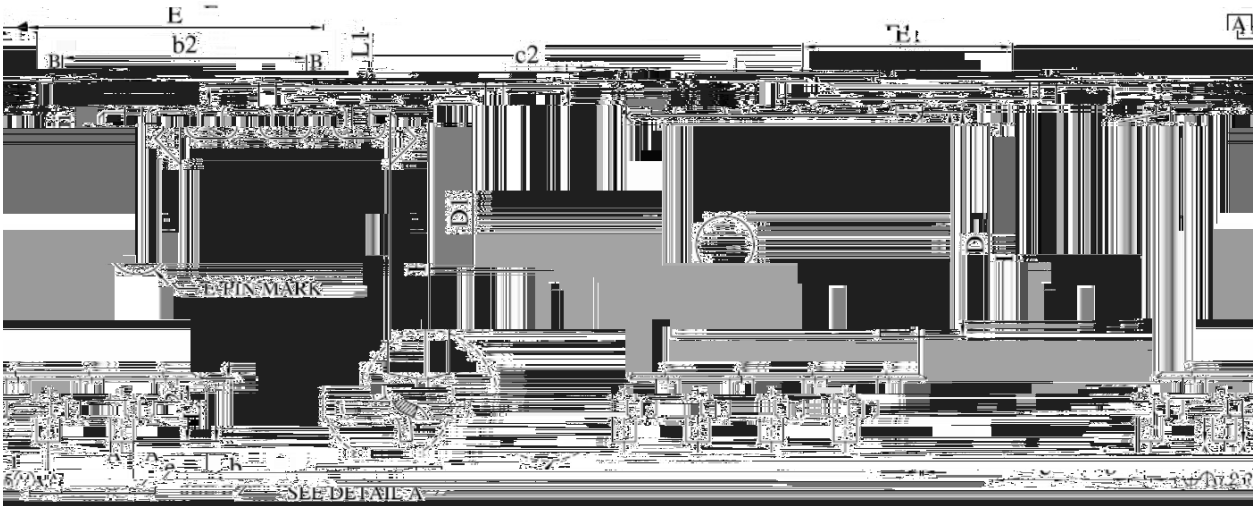
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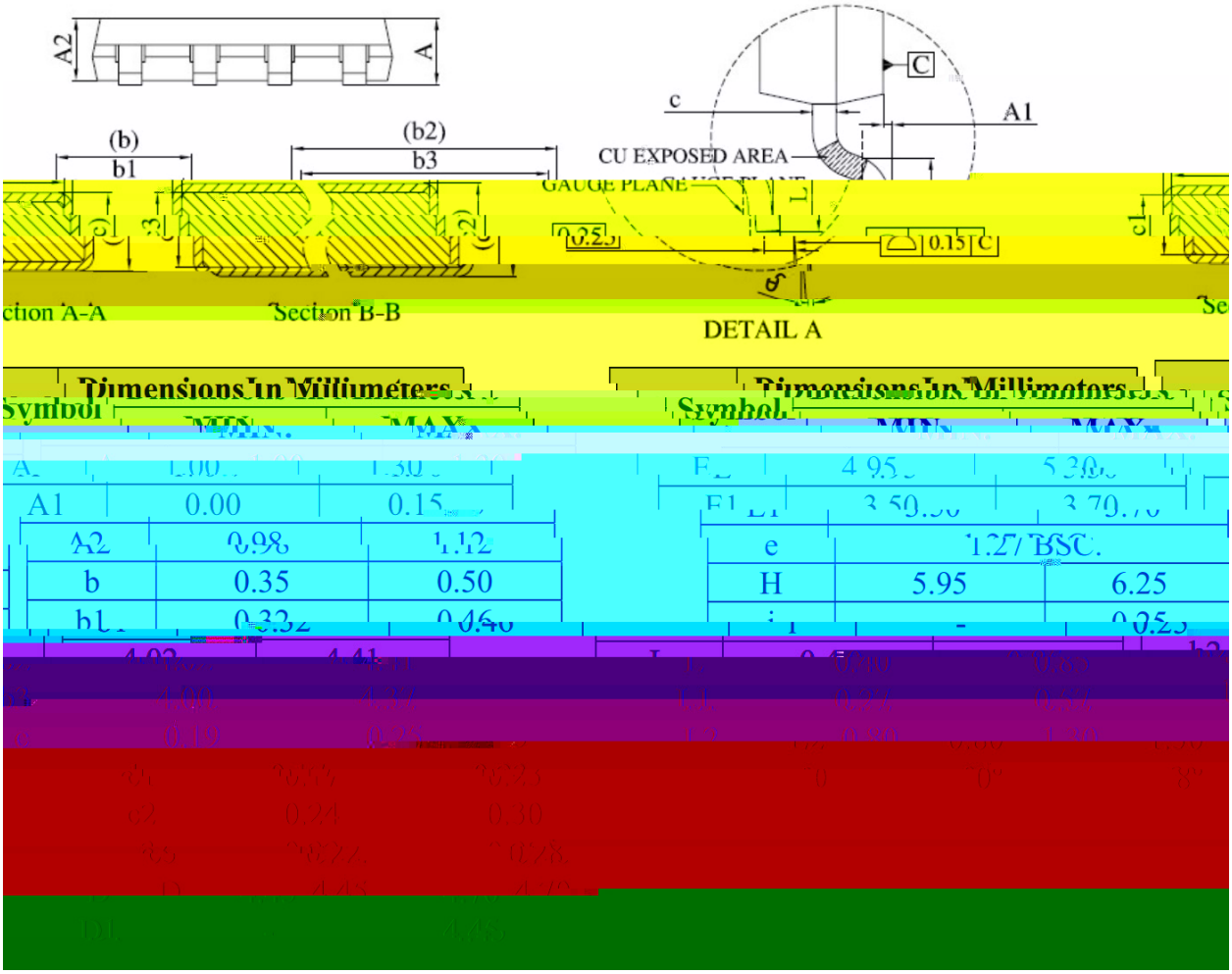
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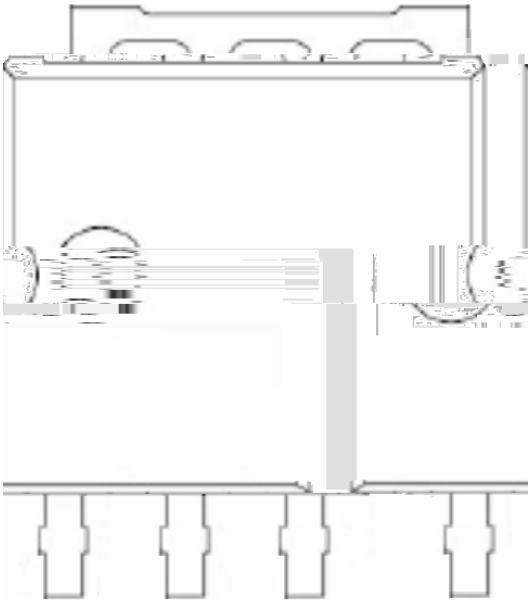

450
400
350
400
350
300


2000
1000
100us
2
Duty = 0.5
0.1
0.01
Mounted on 1in² pad
R θJC : 0.4 °C/W
1E-3
0.01
0.1
0.01
0.1
1
10
100 300
0.02
1E-4


600
4.5
3.5
3.0


E
b2
B1
B
c2
E1
A
D1
D
PIN MARK
SEE DETAIL A


A2
A
(b)
b1
(b2)
b3
c
A1
C
CU EXPOSED AREA
GAUGE PLANE
L
L1
c1
0.25
0.15 C
θ
ction A-A
Section B-B
DETAIL A
Dimensions In Millimeters
Symbol
MIN.
MAX.
A1 0.00 0.15
A2 0.98 1.12
b 0.35 0.50
e 1.27 BSC.
H 5.95 6.25



BR

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Temperature Profile for IR Reflow Soldering(Pb-Free)

± ± ± ±

± ±

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box